

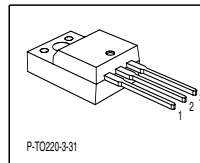
Cool MOS™ Power Transistor

Feature

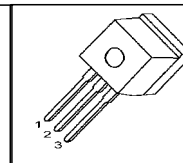
- New revolutionary high voltage technology
- Ultra low gate charge
- Periodic avalanche rated
- Extreme dv/dt rated
- High peak current capability
- Improved transconductance
- PG-TO-220-3-31;-3-111: Fully isolated package (2500 VAC; 1 minute)
- Pb-free lead plating; RoHS compliant
- Qualified according to JEDEC⁰⁾ for target applications

$V_{DS} @ T_{jmax}$	650	V
$R_{DS(on)}$	0.6	Ω
I_D	7.3	A

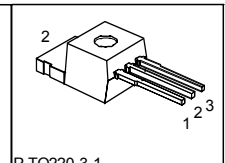
PG-TO220FP



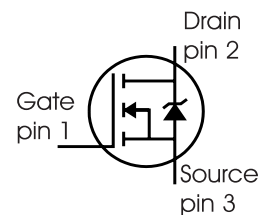
PG-TO262



PG-TO220



Type	Package	Ordering Code	Marking
SPP07N60C3	PG-TO220-3	Q67040-S4400	07N60C3
SPI07N60C3	PG-TO262	Q67040-S4424	07N60C3
SPA07N60C3	PG-TO220FP	SP000216303	07N60C3



Maximum Ratings

Parameter	Symbol	Value		Unit
		SPP_I	SPA	
Continuous drain current $T_C = 25^\circ\text{C}$ $T_C = 100^\circ\text{C}$	I_D	7.3 4.6	7.3 ¹⁾ 4.6 ¹⁾	A
Pulsed drain current, t_p limited by T_{jmax}	$I_{D \text{ puls}}$	21.9	21.9	A
Avalanche energy, single pulse $I_D=5.5\text{A}$, $V_{DD}=50\text{V}$	E_{AS}	230	230	mJ
Avalanche energy, repetitive t_{AR} limited by T_{jmax} ²⁾ $I_D=7.3\text{A}$, $V_{DD}=50\text{V}$	E_{AR}	0.5	0.5	
Avalanche current, repetitive t_{AR} limited by T_{jmax}	I_{AR}	7.3	7.3	A
Gate source voltage static	V_{GS}	± 20	± 20	V
Gate source voltage AC ($f > 1\text{Hz}$)	V_{GS}	± 30	± 30	
Power dissipation, $T_C = 25^\circ\text{C}$	P_{tot}	83	32	W
Operating and storage temperature	T_j, T_{stg}	-55...+150		$^\circ\text{C}$
Reverse diode dv/dt ⁶⁾	dv/dt	15		V/ns

Maximum Ratings

Parameter	Symbol	Value	Unit
Drain Source voltage slope $V_{DS} = 480 \text{ V}$, $I_D = 7.3 \text{ A}$, $T_j = 125 \text{ }^\circ\text{C}$	dv/dt	50	V/ns

Thermal Characteristics

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Thermal resistance, junction - case	R_{thJC}	-	-	1.5	K/W
Thermal resistance, junction - case, FullPAK	$R_{thJC \text{ FP}}$	-	-	3.9	
Thermal resistance, junction - ambient, leaded	R_{thJA}	-	-	62	
Thermal resistance, junction - ambient, FullPAK	$R_{thJA \text{ FP}}$	-	-	80	
SMD version, device on PCB: @ min. footprint @ 6 cm ² cooling area ³⁾	R_{thJA}	-	-	62	
		-	35	-	
Soldering temperature, wavesoldering 1.6 mm (0.063 in.) from case for 10s	T_{sold}	-	-	260	°C

Electrical Characteristics, at $T_j=25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=0\text{V}$, $I_D=0.25\text{mA}$	600	-	-	V
Drain-Source avalanche breakdown voltage	$V_{(BR)DS}$	$V_{GS}=0\text{V}$, $I_D=7.3\text{A}$	-	700	-	
Gate threshold voltage	$V_{GS(th)}$	$I_D=350\mu\text{A}$, $V_{GS}=V_{DS}$	2.1	3	3.9	
Zero gate voltage drain current	I_{DSS}	$V_{DS}=600\text{V}$, $V_{GS}=0\text{V}$, $T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$	-	0.5	1	μA
			-	-	100	
Gate-source leakage current	I_{GSS}	$V_{GS}=30\text{V}$, $V_{DS}=0\text{V}$	-	-	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=10\text{V}$, $I_D=4.6\text{A}$ $T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$	-	0.54	0.6	Ω
			-	1.46	-	
Gate input resistance	R_G	$f=1\text{MHz}$, open drain	-	0.8	-	

Electrical Characteristics, at $T_j = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Characteristics						
Transconductance	g_{fs}	$V_{DS} \geq 2 \cdot I_D \cdot R_{DS(on)max}$, $I_D = 4.6A$	-	6	-	S
Input capacitance	C_{iss}	$V_{GS} = 0V$, $V_{DS} = 25V$, $f = 1MHz$	-	790	-	pF
Output capacitance	C_{oss}		-	260	-	
Reverse transfer capacitance	C_{rss}		-	16	-	
Effective output capacitance, ⁴⁾ energy related	$C_{o(er)}$	$V_{GS} = 0V$, $V_{DS} = 0V$ to 480V	-	30	-	
Effective output capacitance, ⁵⁾ time related	$C_{o(tr)}$		-	55	-	
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 380V$, $V_{GS} = 0/13V$, $I_D = 7.3A$, $R_G = 12\Omega$, $T_j = 125^{\circ}C$	-	6	-	ns
Rise time	t_r		-	3.5	-	
Turn-off delay time	$t_{d(off)}$		-	60	100	
Fall time	t_f		-	7	15	

Gate Charge Characteristics

Gate to source charge	Q_{gs}	$V_{DD} = 480\text{V}$, $I_D = 7.3\text{A}$	-	3	-	nC
Gate to drain charge	Q_{gd}		-	9.2	-	
Gate charge total	Q_g	$V_{DD} = 480\text{V}$, $I_D = 7.3\text{A}$, $V_{GS} = 0 \text{ to } 10\text{V}$	-	21	27	
Gate plateau voltage	$V_{(plateau)}$	$V_{DD} = 480\text{V}$, $I_D = 7.3\text{A}$	-	5.5	-	V

⁰J-STD20 and JESD22

¹Limited only by maximum temperature

²Repetitive avalanche causes additional power losses that can be calculated as $P_{AV} = E_{AR} \cdot f$.

³Device on 40mm*40mm*1.5mm epoxy PCB FR4 with 6cm² (one layer, 70 µm thick) copper area for drain connection. PCB is vertical without blown air.

⁴ $C_{o(er)}$ is a fixed capacitance that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .

⁵ $C_{o(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .

⁶ $I_{SD} \leq I_D$, $di/dt \leq 400\text{A}/\mu\text{s}$, $V_{DClamp} = 400\text{V}$, $V_{peak} < V_{BR, DSS}$, $T_j < T_{j,max}$.

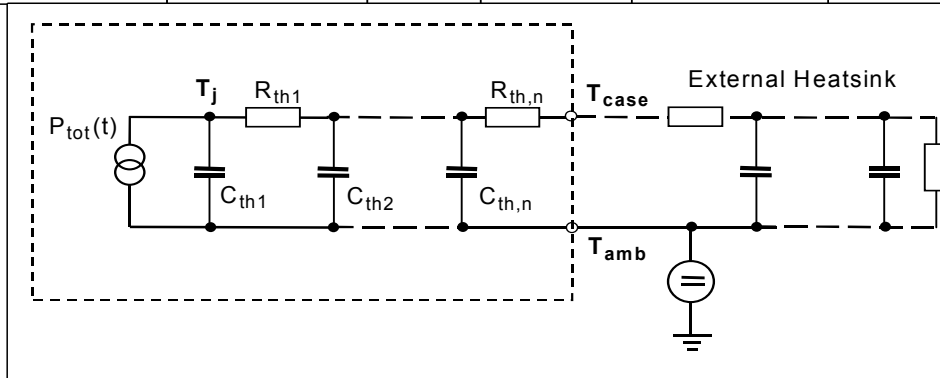
Identical low-side and high-side switch.

Electrical Characteristics

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Inverse diode continuous forward current	I_S	$T_C=25^\circ\text{C}$	-	-	7.3	A
Inverse diode direct current, pulsed	I_{SM}		-	-	21.9	
Inverse diode forward voltage	V_{SD}	$V_{GS}=0\text{V}, I_F=I_S$	-	1	1.2	V
Reverse recovery time	t_{rr}	$V_R=480\text{V}, I_F=I_S$	-	400	600	ns
Reverse recovery charge	Q_{rr}	$di_F/dt=100\text{A}/\mu\text{s}$	-	4	-	μC
Peak reverse recovery current	I_{rrm}		-	28	-	A
Peak rate of fall of reverse recovery current	di_{rr}/dt	$T_j=25^\circ\text{C}$	-	800	-	$\text{A}/\mu\text{s}$

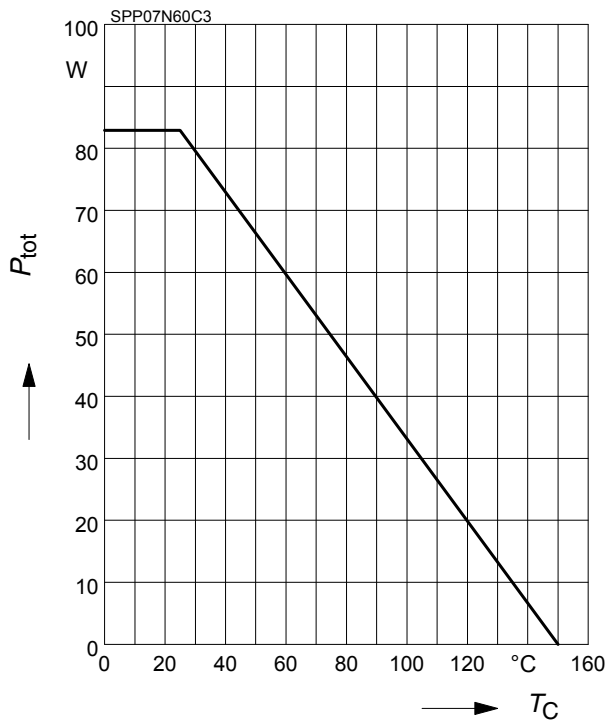
Typical Transient Thermal Characteristics

Symbol	Value		Unit	Symbol	Value		Unit
	SPP_I	SPA			SPP_I	SPA	
R_{th1}	0.024	0.024	K/W	C_{th1}	0.00012	0.00012	Ws/K
R_{th2}	0.046	0.046		C_{th2}	0.0004578	0.0004578	
R_{th3}	0.085	0.085		C_{th3}	0.000645	0.000645	
R_{th4}	0.308	0.195		C_{th4}	0.001867	0.001867	
R_{th5}	0.317	0.45		C_{th5}	0.004795	0.007558	
R_{th6}	0.112	2.511		C_{th6}	0.045	0.412	



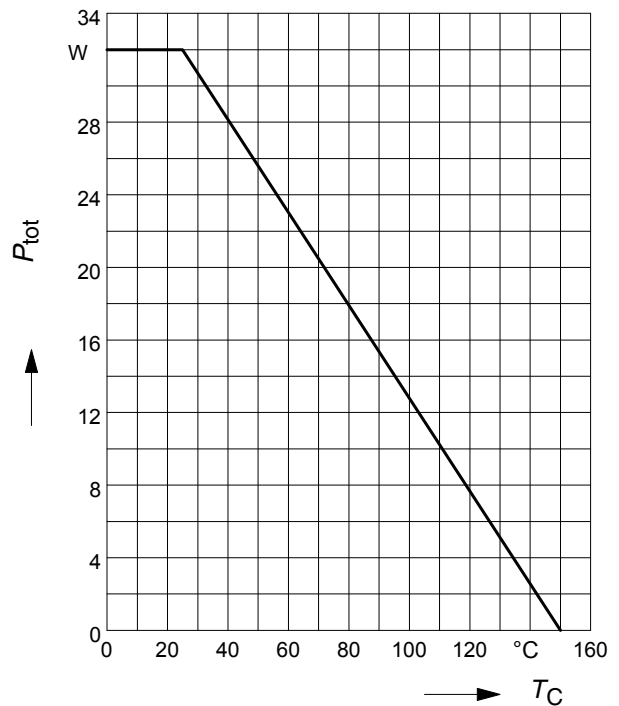
1 Power dissipation

$$P_{\text{tot}} = f(T_C)$$



2 Power dissipation FullPAK

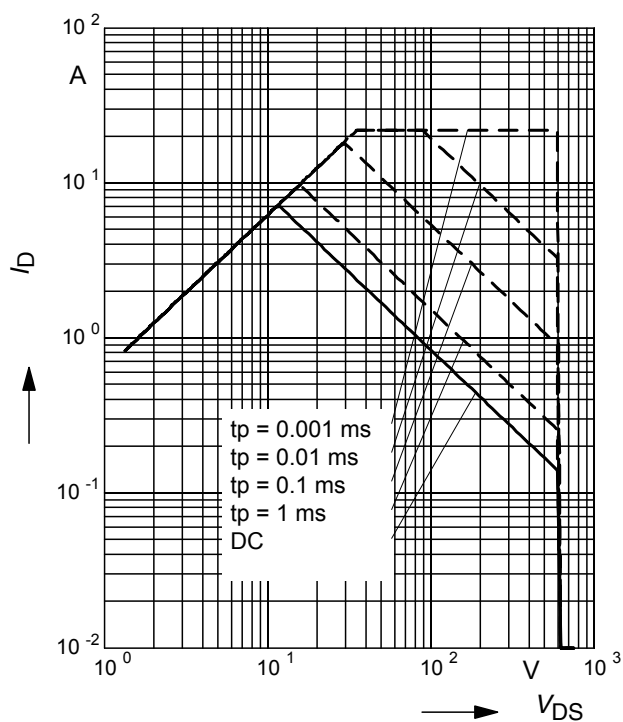
$$P_{\text{tot}} = f(T_C)$$



3 Safe operating area

$$I_D = f(V_{DS})$$

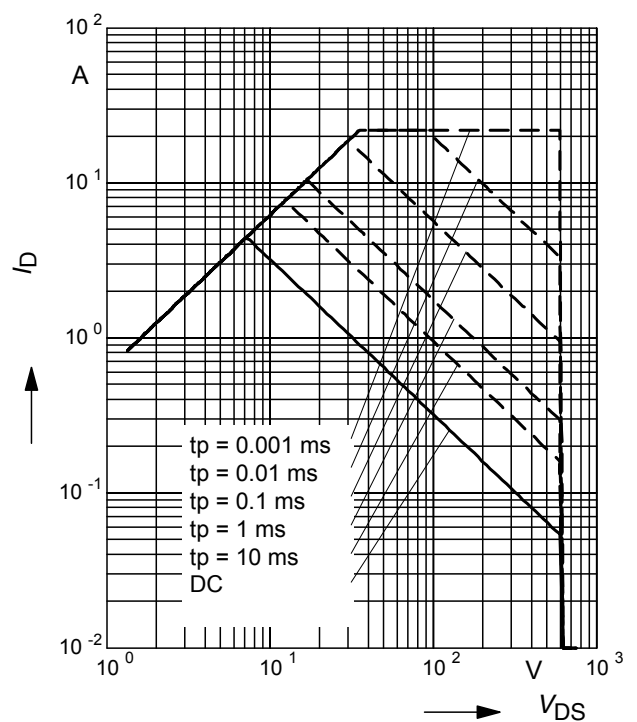
parameter : $D = 0$, $T_C = 25^\circ\text{C}$



4 Safe operating area FullPAK

$$I_D = f(V_{DS})$$

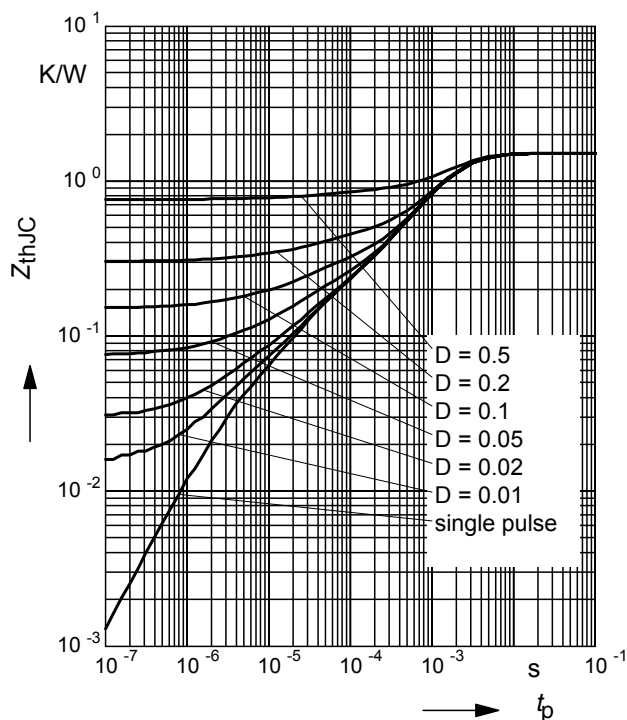
parameter: $D = 0$, $T_C = 25^\circ\text{C}$



5 Transient thermal impedance

$$Z_{thJC} = f(t_p)$$

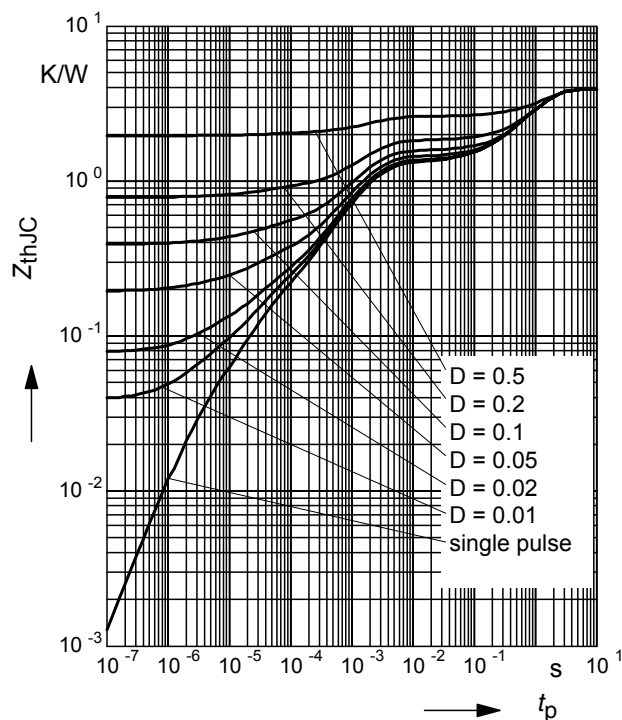
parameter: $D = t_p/T$



6 Transient thermal impedance FullPAK

$$Z_{thJC} = f(t_p)$$

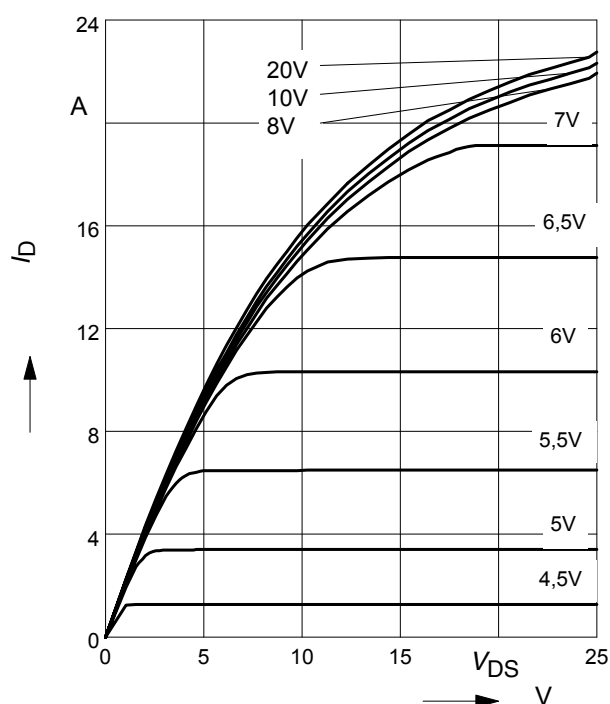
parameter: $D = t_p/t$



7 Typ. output characteristic

$$I_D = f(V_{DS}); T_j = 25^\circ\text{C}$$

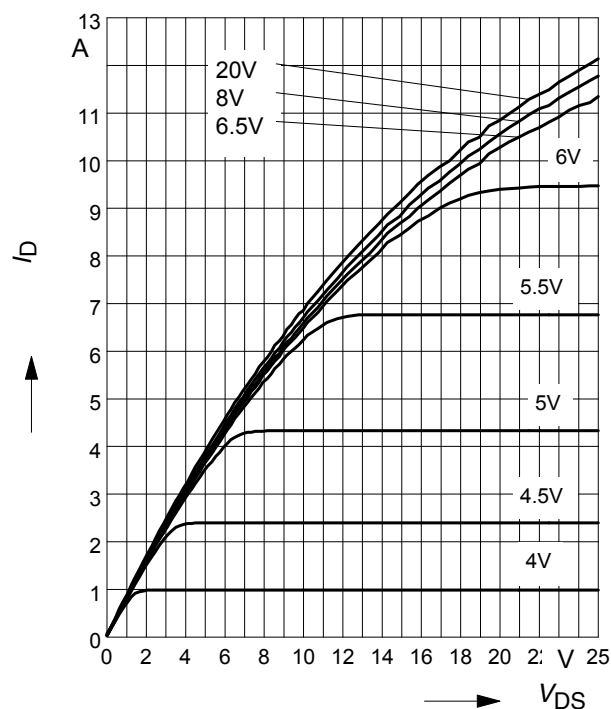
parameter: $t_p = 10 \mu\text{s}, V_{GS}$



8 Typ. output characteristic

$$I_D = f(V_{DS}); T_j = 150^\circ\text{C}$$

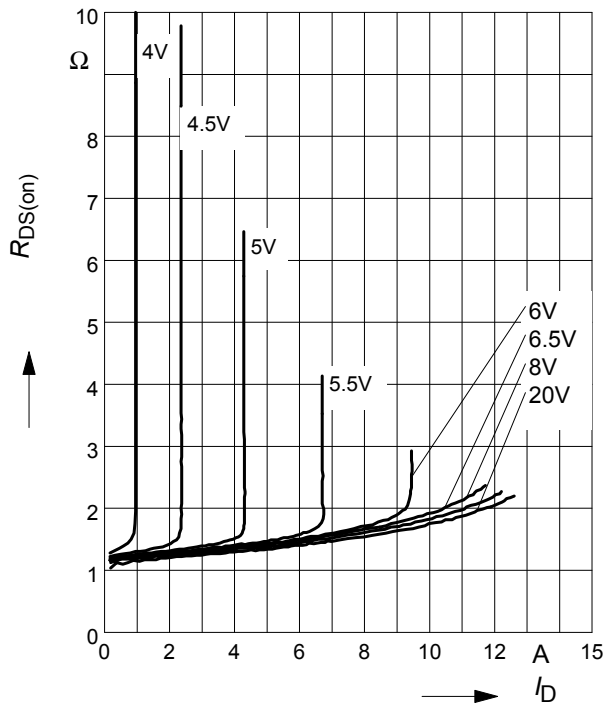
parameter: $t_p = 10 \mu\text{s}, V_{GS}$



9 Typ. drain-source on resistance

$$R_{DS(on)} = f(I_D)$$

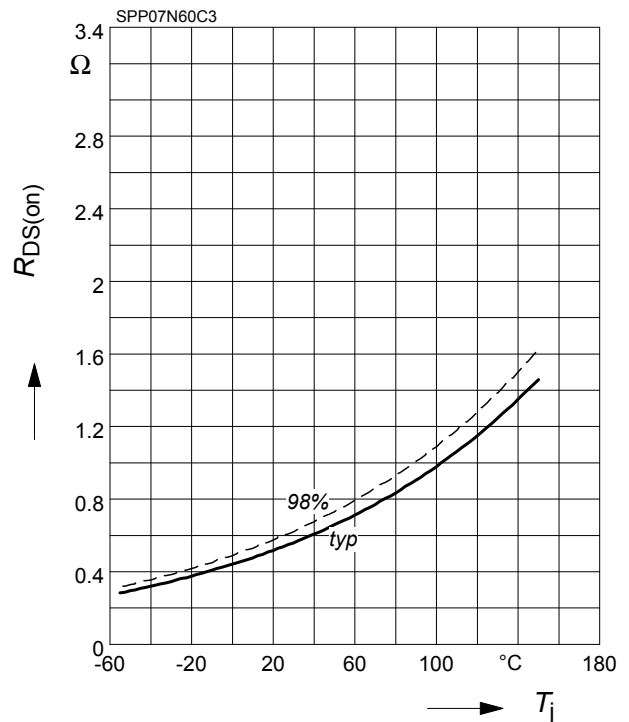
parameter: $T_j = 150^\circ\text{C}$, V_{GS}



10 Drain-source on-state resistance

$$R_{DS(on)} = f(T_j)$$

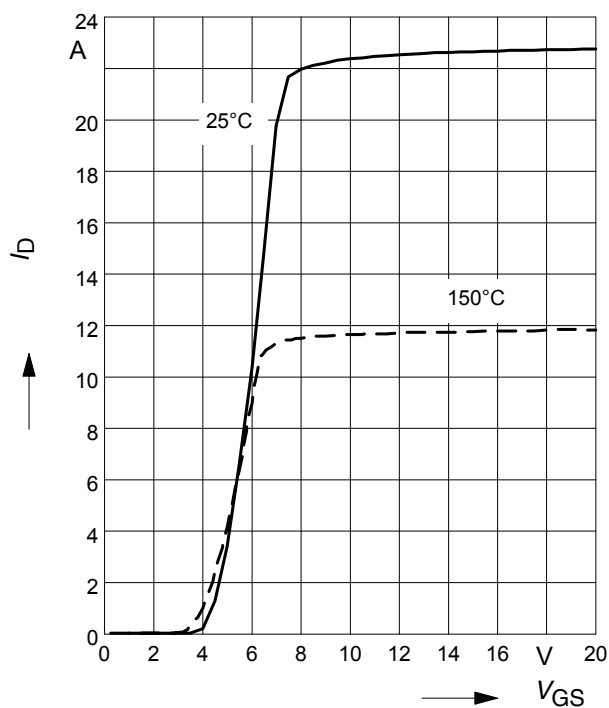
parameter: $I_D = 4.6\text{ A}$, $V_{GS} = 10\text{ V}$



11 Typ. transfer characteristics

$$I_D = f(V_{GS}); V_{DS} \geq 2 \times I_D \times R_{DS(on)max}$$

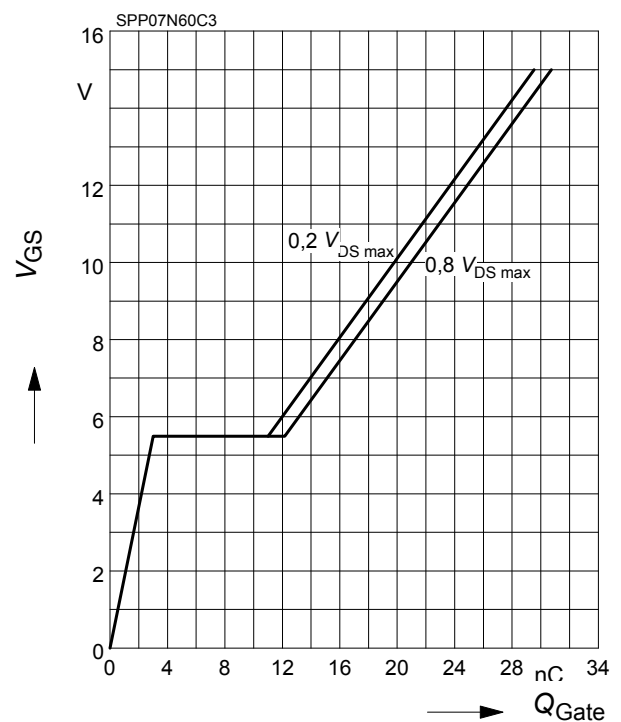
parameter: $t_p = 10\text{ }\mu\text{s}$



12 Typ. gate charge

$$V_{GS} = f(Q_{Gate})$$

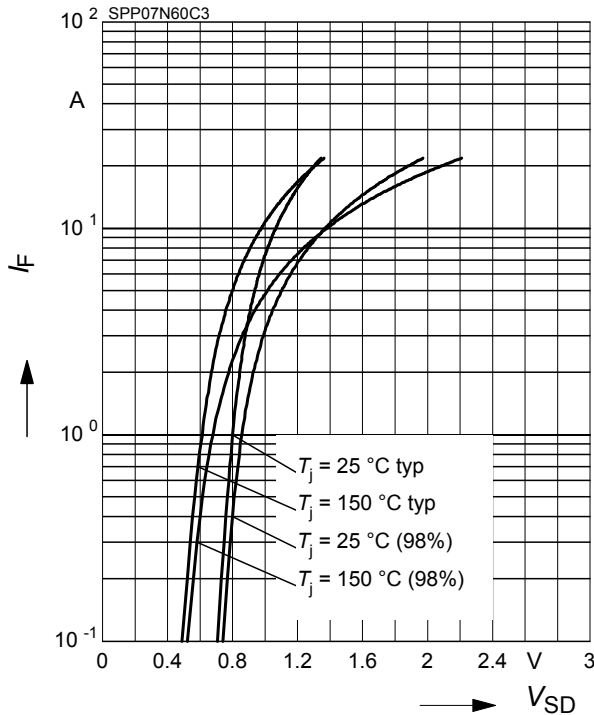
parameter: $I_D = 7.3\text{ A}$ pulsed



13 Forward characteristics of body diode

$$I_F = f(V_{SD})$$

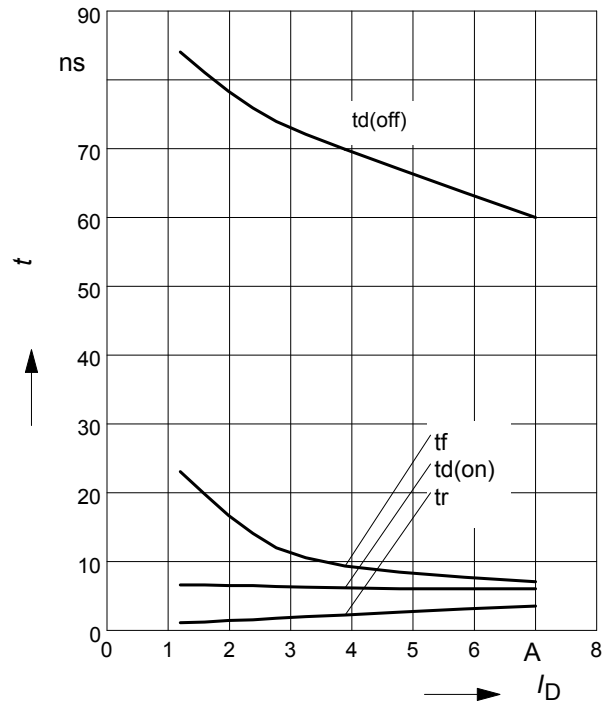
parameter: T_j , $t_p = 10 \mu s$



14 Typ. switching time

$$t = f(I_D), \text{ inductive load, } T_j = 125^\circ C$$

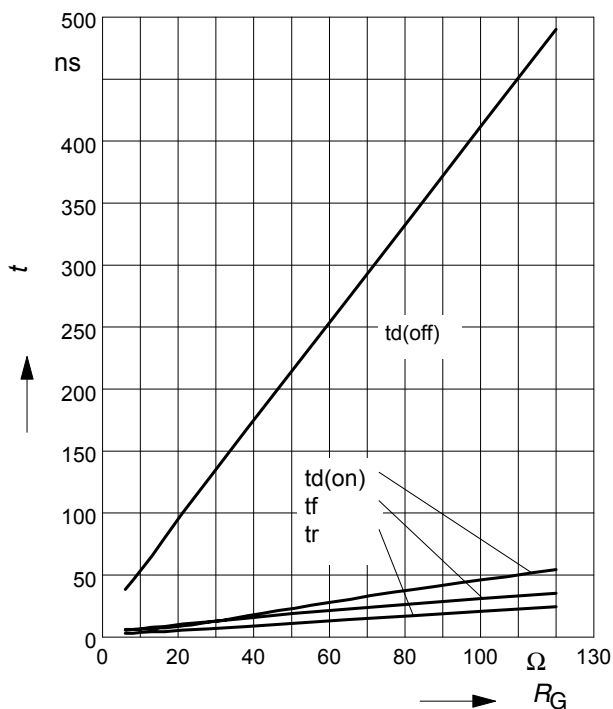
par.: $V_{DS} = 380V$, $V_{GS} = 0/+13V$, $R_G = 12\Omega$



15 Typ. switching time

$$t = f(R_G), \text{ inductive load, } T_j = 125^\circ C$$

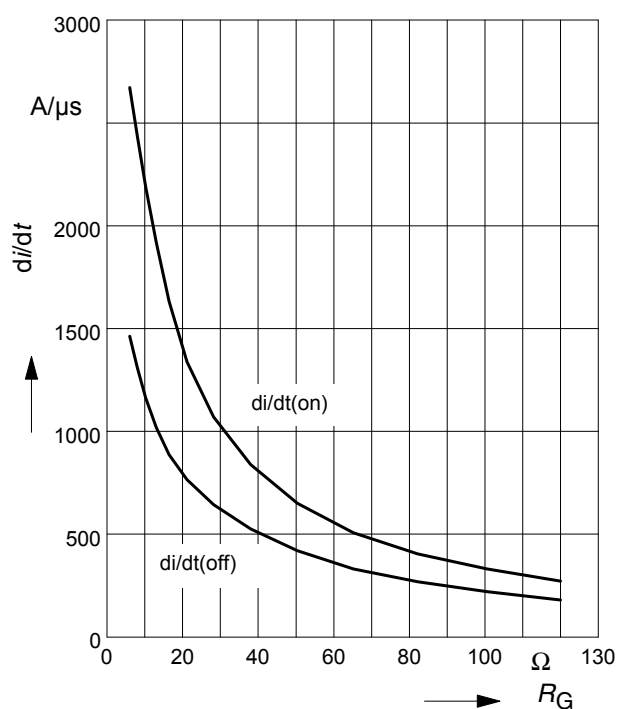
par.: $V_{DS} = 380V$, $V_{GS} = 0/+13V$, $I_D = 7.3 A$



16 Typ. drain current slope

$$di/dt = f(R_G), \text{ inductive load, } T_j = 125^\circ C$$

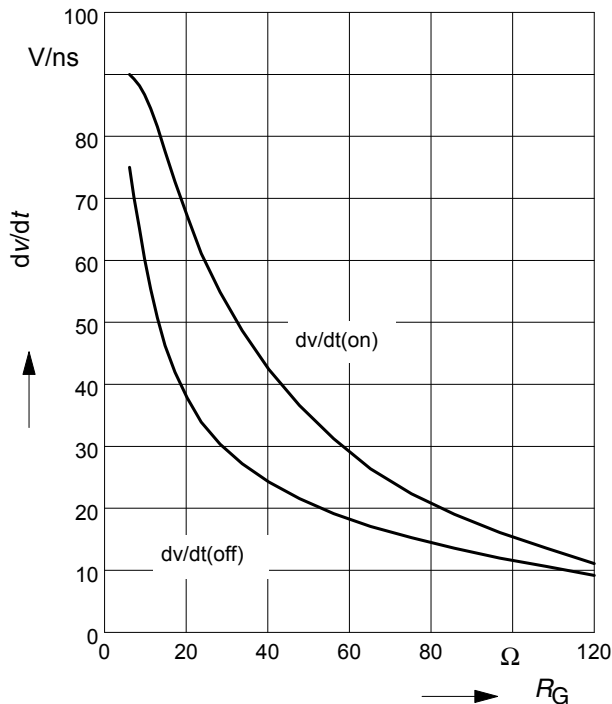
par.: $V_{DS} = 380V$, $V_{GS} = 0/+13V$, $I_D = 7.3A$



17 Typ. drain source voltage slope

$dv/dt = f(R_G)$, inductive load, $T_j = 125^\circ\text{C}$

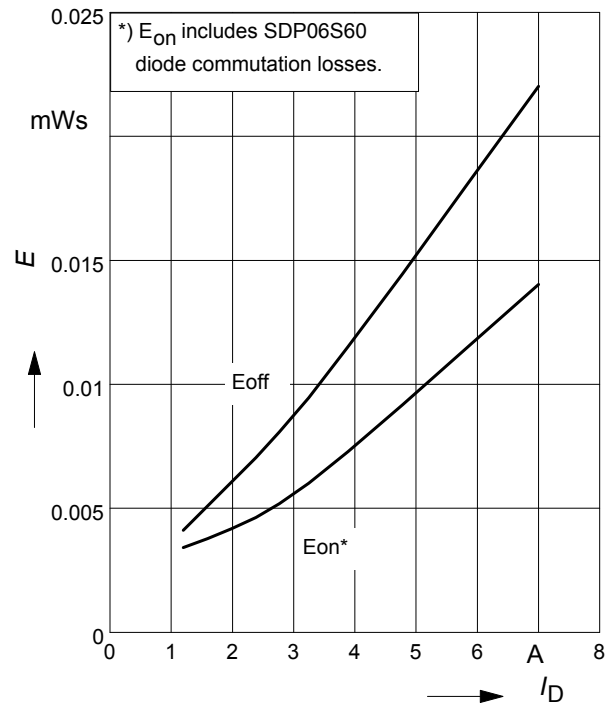
par.: $V_{DS}=380\text{V}$, $V_{GS}=0/+13\text{V}$, $I_D=7.3\text{A}$



18 Typ. switching losses

$E = f(I_D)$, inductive load, $T_j=125^\circ\text{C}$

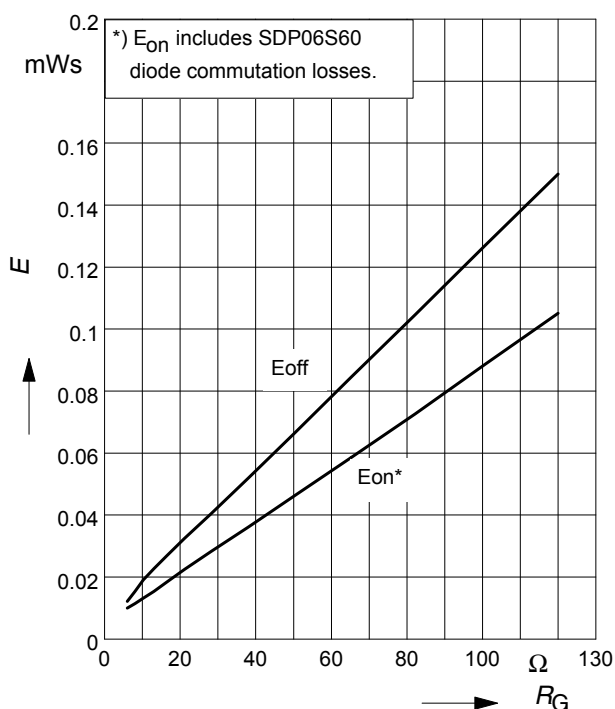
par.: $V_{DS}=380\text{V}$, $V_{GS}=0/+13\text{V}$, $R_G=12\Omega$



19 Typ. switching losses

$E = f(R_G)$, inductive load, $T_j=125^\circ\text{C}$

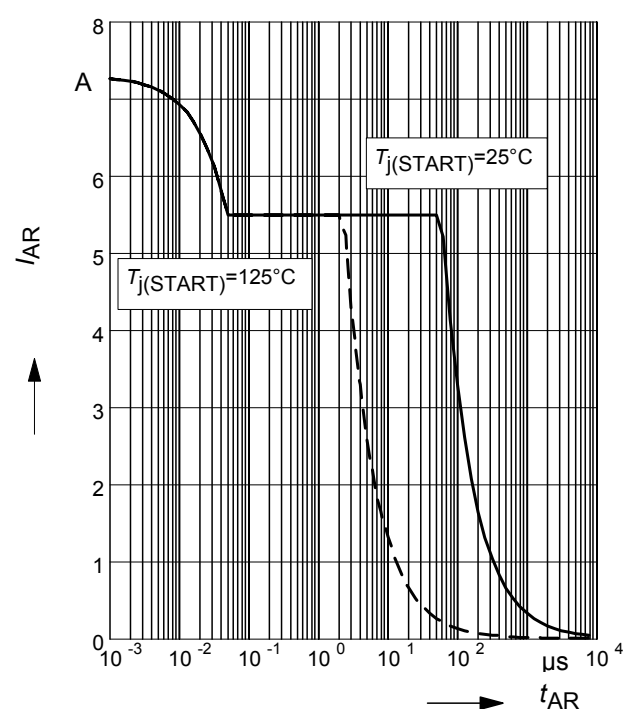
par.: $V_{DS}=380\text{V}$, $V_{GS}=0/+13\text{V}$, $I_D=7.3\text{A}$



20 Avalanche SOA

$I_{AR} = f(t_{AR})$

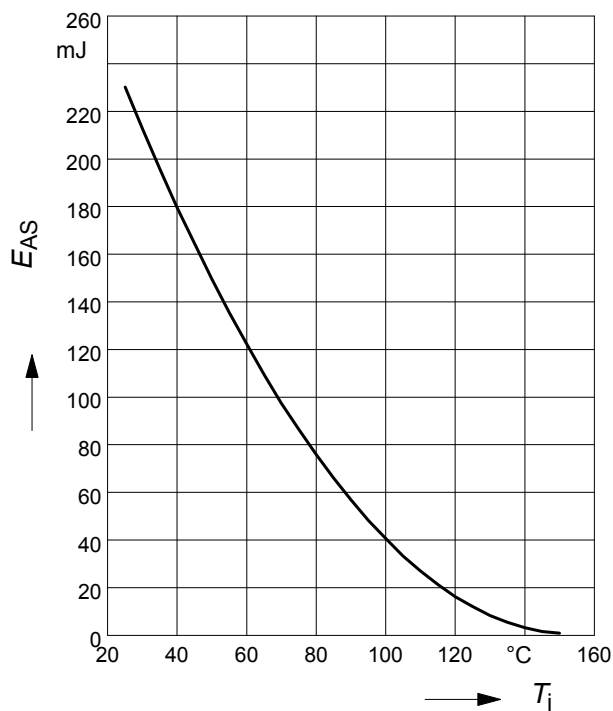
par.: $T_j \leq 150^\circ\text{C}$



21 Avalanche energy

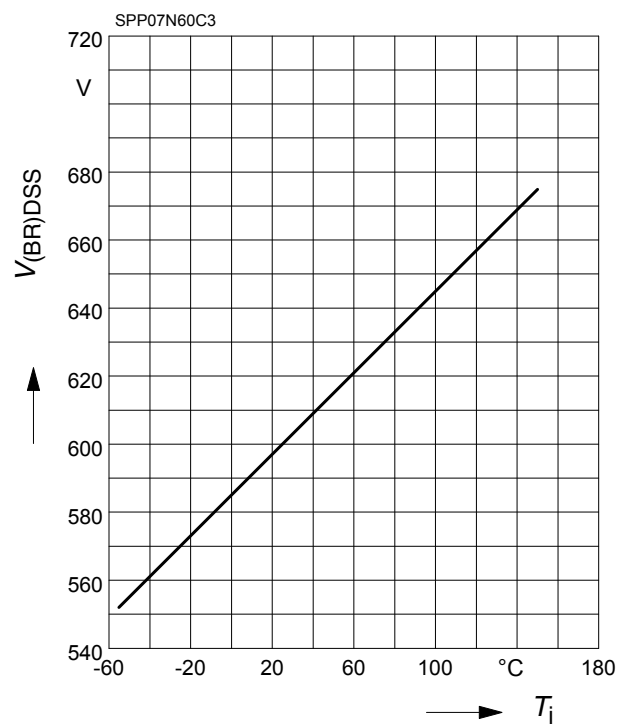
$$E_{AS} = f(T_j)$$

par.: $I_D = 5.5 \text{ A}$, $V_{DD} = 50 \text{ V}$



22 Drain-source breakdown voltage

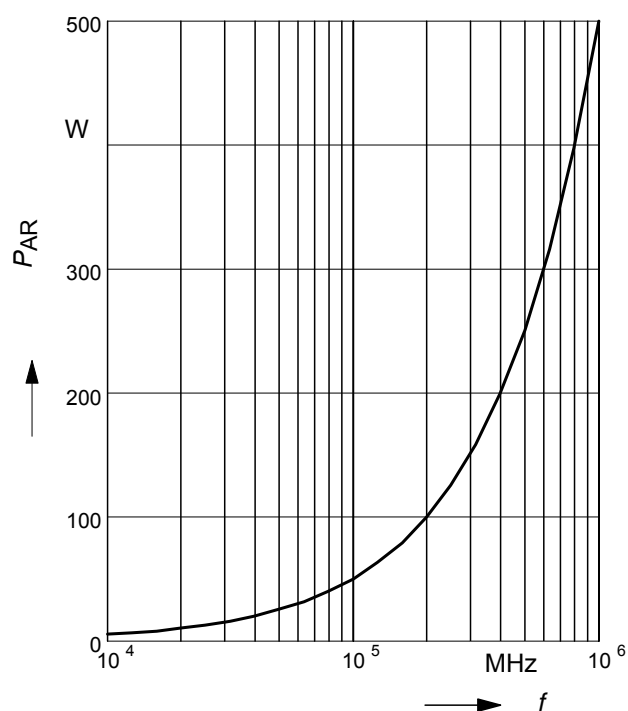
$$V_{(BR)DSS} = f(T_j)$$



23 Avalanche power losses

$$P_{AR} = f(f)$$

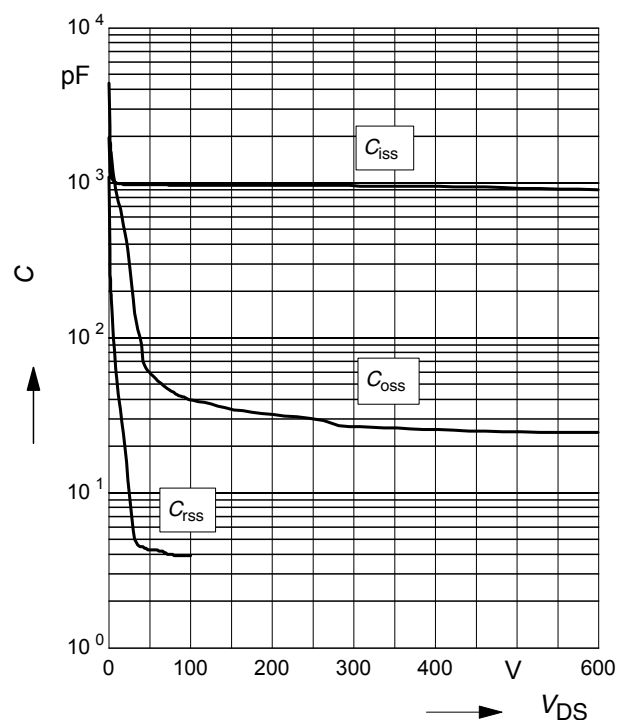
parameter: $E_{AR} = 0.5 \text{ mJ}$



24 Typ. capacitances

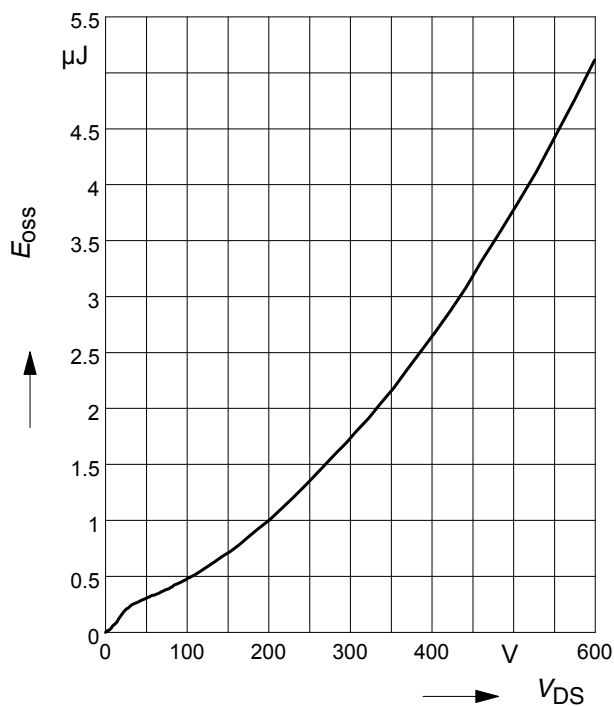
$$C = f(V_{DS})$$

parameter: $V_{GS} = 0 \text{ V}$, $f = 1 \text{ MHz}$

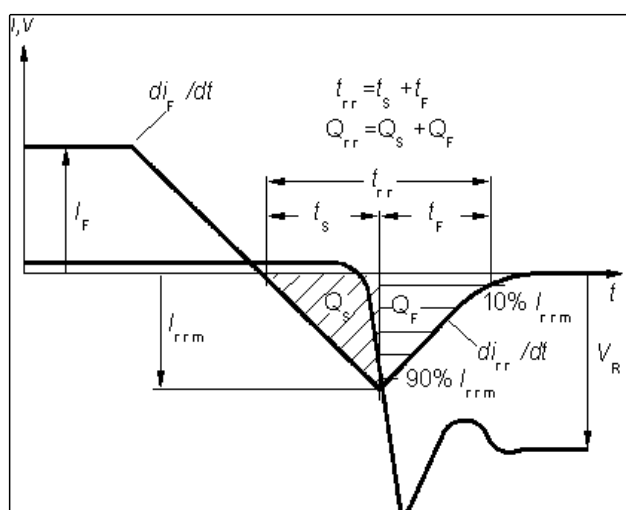


25 Typ. C_{oss} stored energy

$$E_{oss} = f(V_{DS})$$



Definition of diodes switching characteristics



Technical drawing of a mechanical part, showing front, side, and bottom views with dimensions and tolerances.

Front View:

- Overall width: E
- Overall height: D
- Top flange thickness: a
- Inner rectangular hole dimensions: $D1$ (height), $E1$ (width)
- Inner rectangular hole depth: $D2$
- Bottom flange thickness: $L1$
- Overall height from top flange to bottom flange: L
- Three vertical slots with widths $b1$, $b2$, and $b3$
- Slot depths: e (for $b1$ and $b2$), $e1$ (for $b3$)
- Surface texture symbol: $\sqrt{0,355\text{m}} \text{ BA(M)}$ (Point P)

Side View:

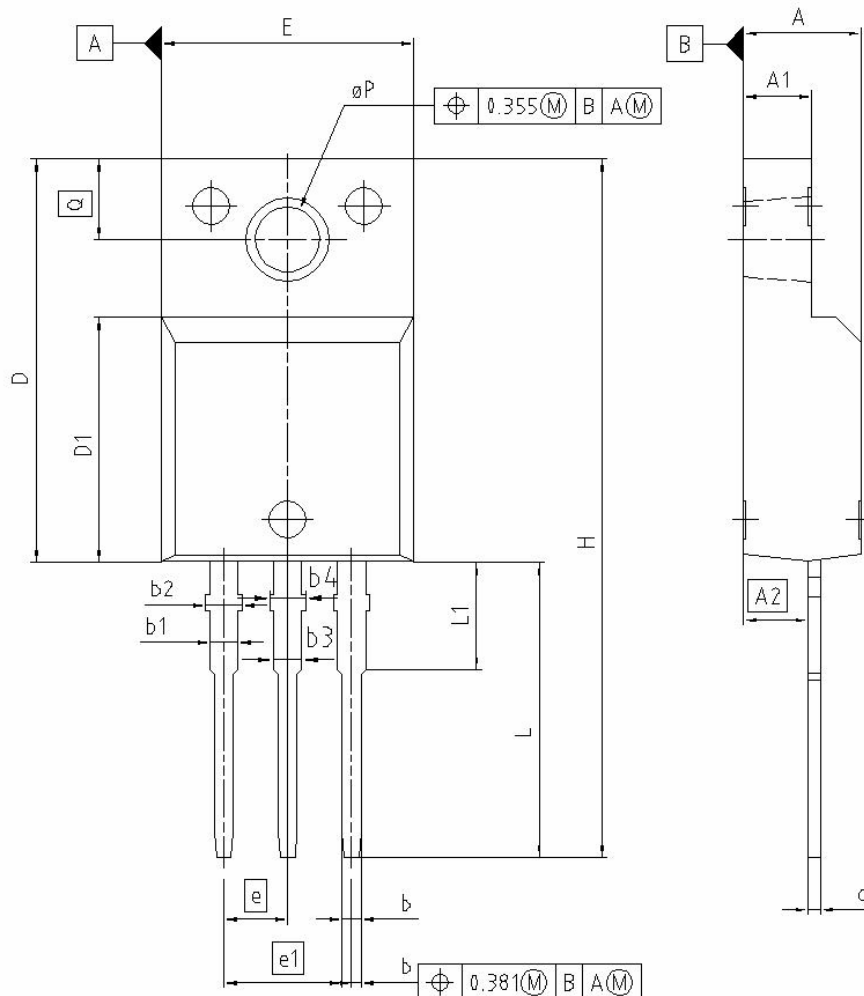
- Overall width: A
- Top flange thickness: $A1$
- Inner rectangular hole depth: H
- Bottom flange thickness: $A2$
- Overall height: H
- Surface texture symbol: $\sqrt{0,1}$

Bottom View:

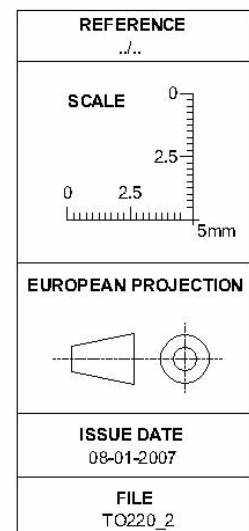
- Overall width: c
- Surface texture symbol: $\sqrt{0,254\text{m}} \text{ BA(M)}$ (Point b)

DOCUMENT NO. Z8B00003318	
SCALE	
EUROPEAN PROJECTION	
ISSUE DATE 23-08-2007	
REVISION 05	

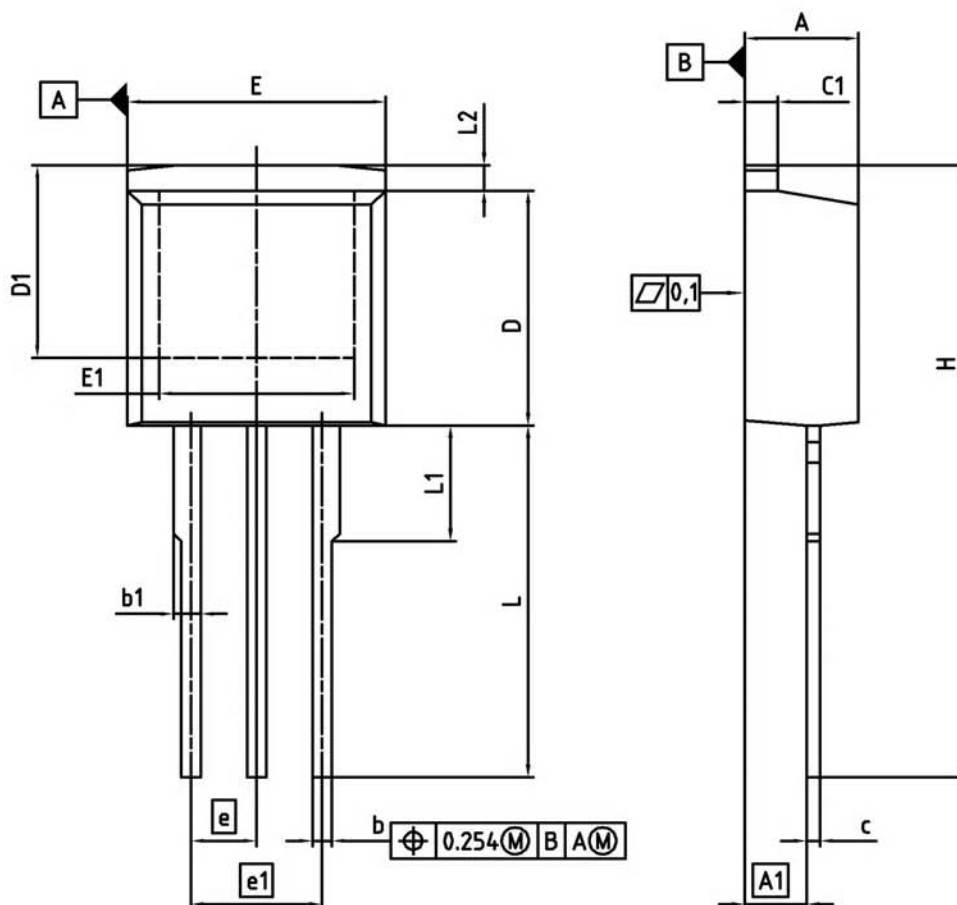
PG-TO220-3-31/3-111 Fully isolated package (2500VAC; 1 minute)



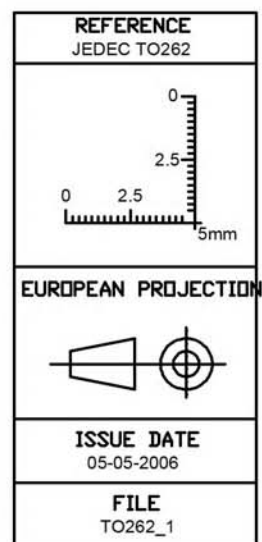
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.55	4.85	0.179	0.191
A1	2.55	2.85	0.100	0.112
A2	2.42	2.72	0.095	0.107
b	0.65	0.85	0.026	0.033
b1	0.95	1.33	0.037	0.052
b2	0.95	1.51	0.037	0.059
b3	0.65	1.33	0.026	0.052
b4	0.65	1.51	0.026	0.059
c	0.40	0.63	0.016	0.025
D	15.85	16.15	0.624	0.636
D1	9.53	9.83	0.375	0.387
E	10.35	10.65	0.407	0.419
e	2.54		0.100	
e1	5.08		0.200	
N	3		3	
H	29.45	29.75	1.159	1.171
L	13.45	13.75	0.530	0.541
L1	3.15	3.45	0.124	0.136
ϕP	2.95	3.20	0.116	0.126
Q	3.15	3.50	0.124	0.138



PG-TO-262-3-1/PG-TO262-3-21 (I²-PAK)



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.300	4.572	0.169	0.180
A1	2.150	2.718	0.085	0.107
b	0.650	0.864	0.026	0.034
b1	0.635	1.400	0.025	0.055
c	0.330	0.600	0.013	0.024
c1	1.170	1.400	0.046	0.055
D	8.509	9.450	0.335	0.372
D1	6.900	-	0.272	-
E	9.700	10.363	0.382	0.408
E1	6.500	8.600	0.256	0.339
e	2.540		0.100	
e1	5.080		0.200	
N	3		3	
L	13.000	14.000	0.512	0.551
L1	-	4.800	-	0.189
L2	-	1.727	-	0.068



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Information

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